



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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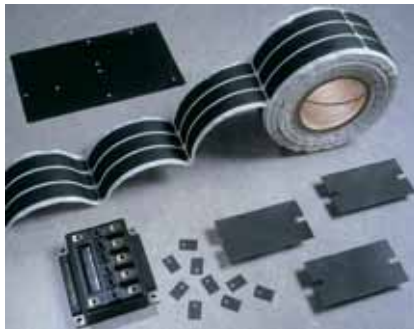
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## Glass-Reinforced Grease Replacement Thermal Interface

### Features and Benefits

- Thermal impedance: 0.35°C-in<sup>2</sup>/W (@50 psi)
- Eliminates processing constraints typically associated with grease
- Conforms to surface textures
- Easy handling
- May be installed prior to soldering and cleaning without worry



Bergquist Q-Pad 3 eliminates problems associated with thermal grease such as contamination of electronic assemblies and reflow solder baths. Q-Pad 3 may be installed prior to soldering and cleaning without worry. When clamped between two surfaces, the elastomer conforms to surface textures thereby creating an air-free interface between heat-generating components and heat sinks.

Fiberglass reinforcement enables Q-Pad 3 to withstand processing stresses without losing physical integrity. It also provides ease of handling during application.

TYPICAL PROPERTIES OF Q-PAD 3						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Black	Black	Visual			
Reinforcement Carrier	Fiberglass	Fiberglass	—			
Thickness (inch) / (mm)	0.005	0.127	ASTM D 374			
Hardness (Shore A)	86	86	ASTM D 2240			
Continuous Use Temp (°F) / (°C)	-76 to 356	-60 to 180	—			
<b>ELECTRICAL</b>						
Dielectric Breakdown Voltage (Vac)	Non-Insulating	Non-Insulating	ASTM D 149			
Dielectric Constant (1000 Hz)	NA	NA	ASTM D 150			
Volume Resistivity (Ohm-meter)	10 <sup>2</sup>	10 <sup>2</sup>	ASTM D 257			
Flame Rating	V-O	V-O	U.L.94			
<b>THERMAL</b>						
Thermal Conductivity (W / m-K)	2.0	2.0	ASTM D 5470			
<b>THERMAL PERFORMANCE vs PRESSURE</b>						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		2.26	1.99	1.76	1.53	1.30
Thermal Impedance (°C-in <sup>2</sup> /W) (1)		0.65	0.48	0.35	0.24	0.16

1) The ASTM D 5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

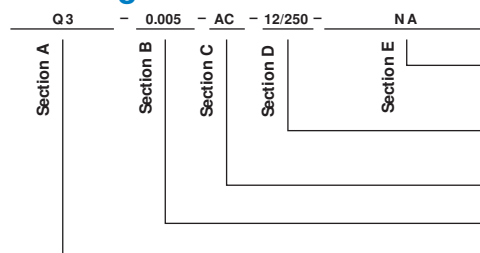
### Typical Applications Include:

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

### Configurations Available:

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

### Building a Part Number



### Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

\_\_\_ = Standard configuration dash number, 1212 = 12" x 12" sheets, 12/250 = 12" x 250' rolls, or 00 = custom configuration

AC = Adhesive, one side  
00 = No adhesive

Standard thicknesses available: 0.005"

Q 3 = Q-Pad 3 Material

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).

Si-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others